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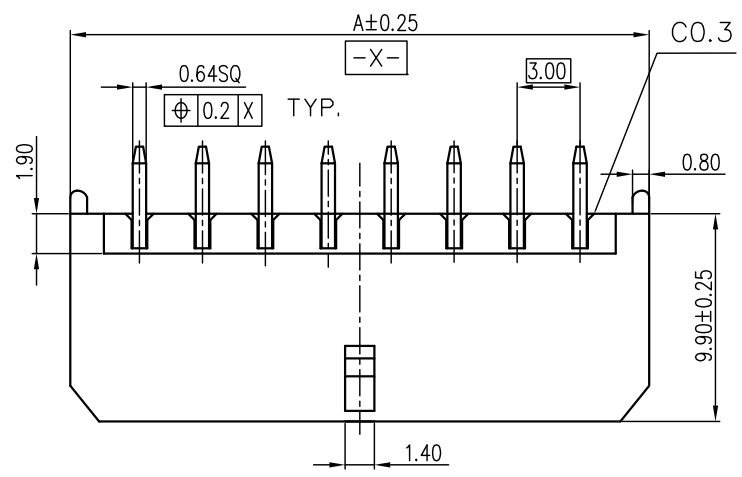
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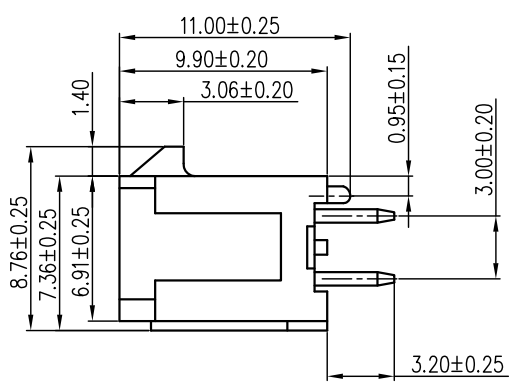
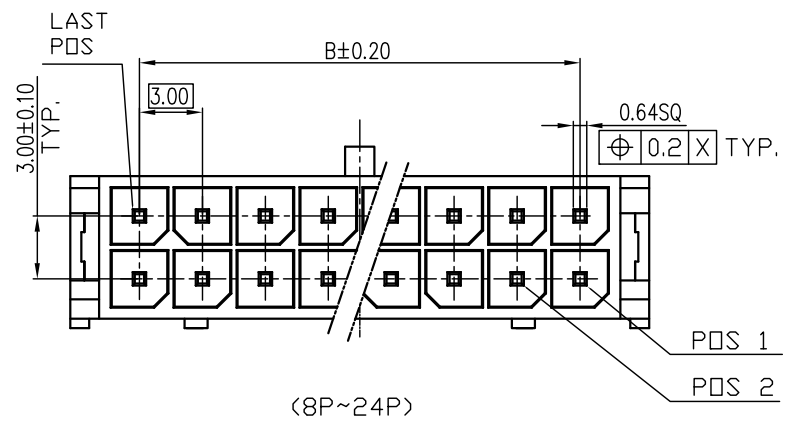
The marking on this product doesn't contain environmental hazardous materials per Material Specification 55-00259 for Sony GP compliant or per directive 2011/65/EU for RoHS compliant.

**PRELIMINARY RELEASE  
SUBJECT TO CHANGE**

REVISIONS				
SYM	ECN No.	DESCRIPTION	DATE	APPROVED
A	NE-12149	RELEASE FOR RoHS	08/16/2012	Arron Lin
B	NE-13034	MODIFY PLATING TO OVERALL	03/13/2013	Arron Lin
CX1		UPDATE FOR 2 POS., PACKING QUANTITY AND PLATING	03/03/2014	Arron Lin



- NOTE:
- INSULATOR: HIGH TEMP. THERMOPLASTIC, LCP, UL 94V-0, COLOR: BLACK.
  - CONTACT MATERIAL: COPPER ALLOY;
  - FINISH:  
CONTACT AREA: SELECTIVE PLATING OPTIONS;  
SOLDERING AREA: MATTE TIN PLATING 100 μ" MIN OR GOLD PLATING;  
UNDER PLATING: NICKEL PLATING 50 μ" THICKNESS MIN. OVERALL.
  - THIS PRODUCT DOESN'T ENVIRONMENTAL HAZARDOUS MATERIALS PER DIRECTIVE 2011/65/EU FOR RoHS.
  - APPLICABLE P.C.BOARD THICKNESS: 1.60mm
  - PACKING MUST BE PER Amphenol PACKING SPECIFICATION



24	39.60	33.00
22	36.60	30.00
20	33.60	27.00
18	30.60	24.00
16	27.60	21.00
14	24.60	18.00
12	21.60	15.00
10	18.60	12.00
08	15.60	9.00
06	12.60	6.00
04	9.60	3.00
02	6.60	NA
NO. OF CIRCUIT	A	B

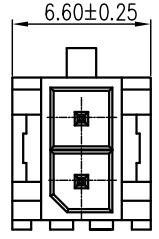
PART NO. G881AXX1X2T3EU  
No. OF CIRCUIT

- CONTACT FINISH
- 0: Tin (OVERALL)
  - 1: FLASH GOLD (OVERALL)
  - 2: 15 μ" GOLD
  - 3: 30 μ" GOLD

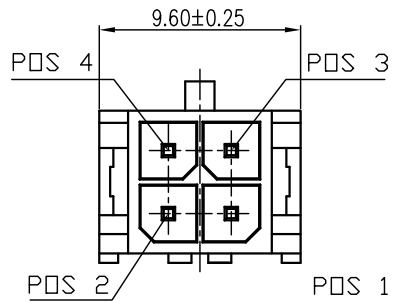
TOLERANCE	APPROVALS	DATE	TITLE		PART No.		
X. ±0.30	DRAWN Debby Hung	03/03/2014	G881A SERIES MICRO POWER, WAFER 3.00 MM PITCH STRAIGHT DIP, W/O KINK		<b>Amphenol</b> ® Amphenol Corporation Amphenol Taiwan Corporation		
X.XX ±0.20	CHECKED Roger Tsai	03/03/2014					
X.XXX ±0.10	APPROVED Arron Lin	03/03/2014					
ANGULAR ±1°	DWG TYPE CUST DWG	PROJECT CODE PHD		UNIT mm	SIZE A3	PART No. G881AXX1X2T3EU	
UNLESS OTHERWISE SPECIFIED				SCALE NA	SHEET 1 OF 3	DWG No. G881AXX1X2T3EU	REV. CX1

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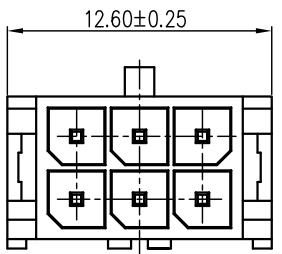
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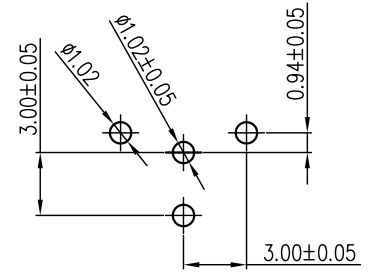
(2X1POS)



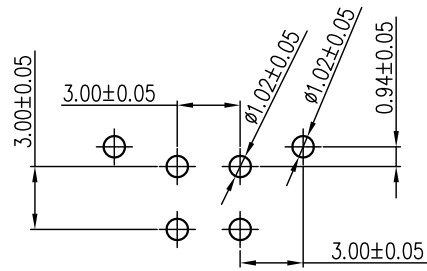
(2X2POS)



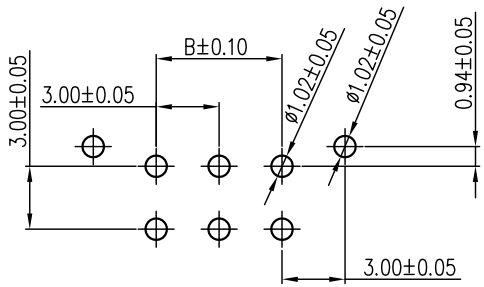
(2X3POS)



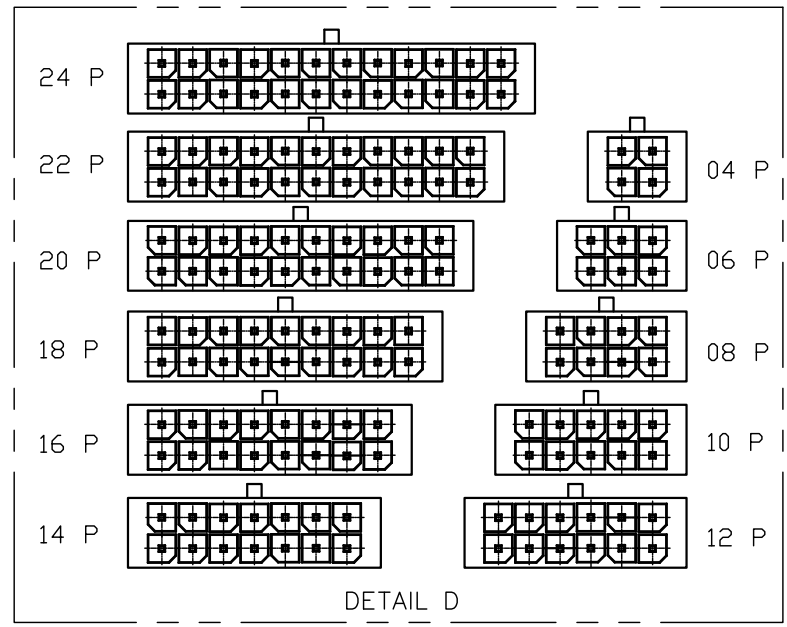
2X1 POSITIONS  
RECOMMENDED PCB LAYOUT



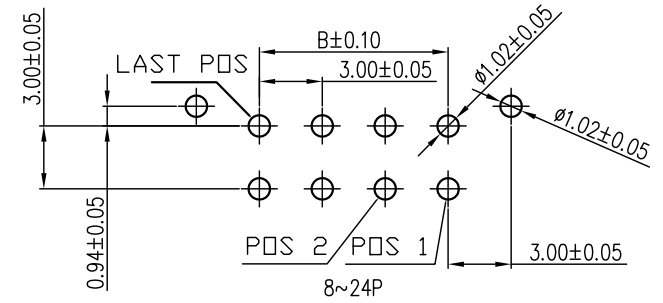
2X2 POSITIONS  
RECOMMENDED PCB LAYOUT



2X3 POSITIONS  
RECOMMENDED PCB LAYOUT



DETAIL D



8~24P  
RECOMMENDED PCB LAYOUT

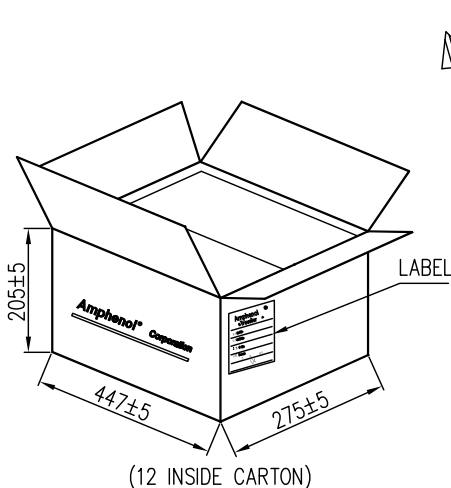
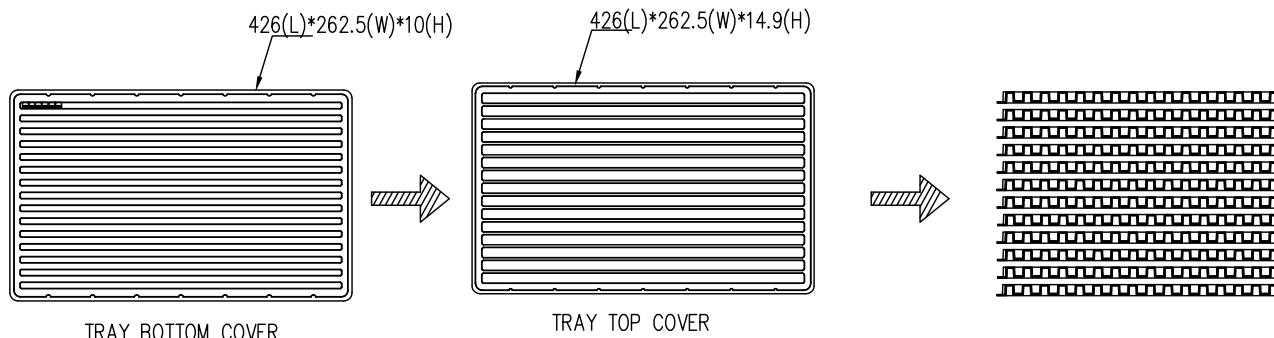
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TOLERANCE		APPROVALS		DATE	TITLE		Amphenol®			
X.		DRAWN	Debby Hung	03/03/2014	G881A SERIES MICRO POWER, WAFER 3.00 MM PITCH STRAIGHT DIP, W/O KINK		Amphenol Corporation Amphenol Taiwan Corporation			
X.X	±0.30	CHECKED	Roger Tsai	03/03/2014						
X.XX	±0.20	APPROVED	Arron Lin	03/03/2014						
X.XXX	±0.10	DWG TYPE		PROJECT CODE	UNIT	SCALE	SIZE	PART No.	DWG No.	REV.
ANGULAR	±1°	CUST DWG		PHD	mm	NA	A3	G881AXX1X2T3EU	G881AXX1X2T3EU	CX1
UNLESS OTHERWISE SPECIFIED							2 OF 3			

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POS	PCS/TRAY	PCS/CARTON
02	900	10800
04	615	7380
06	465	5580
08	375	4500
10	315	3780
12	270	3240
14	240	2880
16	210	2520
18	180	2160
20	165	1980
22	150	1800
24	150	1800

NOTE:  
 1. MATERIAL : BLACK CONDUCTIVE POLYSTYRENE ALLOY  
 2. ALL DIMENSIONS MEET EIA-481-C REQUIREMENTS.  
 3. THICKNESS : 0.80±0.05mm.

TOLERANCE	APPROVALS	DATE	TITLE		Amphenol <sup>®</sup> Amphenol Corporation Amphenol Taiwan Corporation		
X. ±0.30	DRAWN Debby Hung	03/03/2014	G881A SERIES MICRO POWER, WAFER 3.00 MM PITCH STRAIGHT DIP, W/O KINK		UNIT mm	SIZE A3	PART No. G881AXX1X2T3EU
X.XX ±0.20	CHECKED Roger Tsai	03/03/2014			SCALE NA	SHEET 3 OF 3	DWG No. G881AXX1X2T3EU
X.XXX ±0.10	APPROVED Arron Lin	03/03/2014			REV. CX1		
ANGULAR ±1°	DWG TYPE CUST DWG	PROJECT CODE PHD					
UNLESS OTHERWISE SPECIFIED							